

Appl. No. 09/665,034
Amdt. Dated 08/05/2004
Reply to Office action of April 6, 2004

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-13. (Cancelled).

14. (Currently Amended) The method as recited in claim ~~13~~15, wherein
the conductive strip is formed by plating a conductive material onto the inner side surface
of the bond shelf.

15. (Currently Amended) ~~A The method as recited in claim 13, wherein for assembling an~~
electronic package, comprising:

forming a housing which has a bond pad located on a top surface of a bond shelf, the
bond shelf having an inner side surface along a thickness of the bond shelf;

forming a conductive strip lengthwise along the inner side surface of the bond shelf; and
removing a portion of the conductive strip along the inner side surface of the bond shelf
to form a pair of separate conductive strips lengthwise along the inner side surface of the bond
shelf, the portion of the conductive strip is removed by drilling a portion of the inner side surface
of the bond shelf including the conductive strip.

16. (Currently Amended) The method as recited in claim ~~13~~15, further comprising:
mounting an integrated circuit to the housing and connecting the integrated circuit to the
bond pad.

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17. (Previously Presented) The method as recited in claim 14, wherein
the portion of the conductive strip is removed by
etching away a portion of the conductive material on the inner side surface of the
bond shelf.
18. (Currently Amended) The method as recited in claim ~~13~~15, wherein
the conductive strip is formed along the ~~second~~ inner side surface of the bond shelf by
masking surfaces of the bond shelf except for portions of the bond shelf to be
plated, the inner side surface of the bond shelf being unmasked, and
plating a conductive material onto the inner side surface of the bond shelf.
19. (Previously Presented) The method as recited in claim 18, wherein
the conductive material is copper, and
the conductive strip is further formed by plating gold onto the copper.
20. (Currently Amended) A. The method as recited in claim 19, wherein for assembling an
electronic package, comprising:
forming a housing which has a bond pad located on a top surface of a bond shelf, the
bond shelf having an inner side surface along a thickness of the bond shelf;
forming a conductive strip lengthwise along the inner side surface of the bond shelf; and
removing a portion of the conductive strip along the inner side surface of the bond shelf
to form a pair of separate conductive strips lengthwise along the inner side surface of the bond
shelf, the portion of the conductive strip is removed by drilling a portion of the bond shelf.

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21-34. (Cancelled)

35. (Withdrawn) The method as recited in claim ~~13~~15, wherein
the forming of the conductive strip further includes

forming a portion of the conductive strip around onto the top surface of the bond
shelf to couple to the bond pad on the top surface of the bond shelf.

36. (Withdrawn) The method as recited in claim 35, wherein

the portion of the conductive strip around on the top surface of the bond shelf to
further anchor the conductive strip to the housing.

37. (Withdrawn) The method as recited in claim ~~13~~15, wherein
the forming of the conductive strip further includes

forming a portion of the conductive strip around onto the top surface of the bond
shelf to form another bond pad on the top surface of the bond shelf.

38. (Withdrawn) The method as recited in claim 37, wherein

the portion of the conductive strip around on the top surface of the bond shelf to
further anchor the conductive strip to the housing.

39. (Cancelled).

40. (Currently Amended) A The method of claim 39, wherein for assembling an electronic
package, comprising:

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forming a housing which has a bond pad located on a top surface of a bond shelf, the bond shelf having an inside surface along an edge of the bond shelf;

plating a conductive material along the inside surface of the bond shelf; and

removing a portion of the conductive material along the inside surface of the bond shelf to form a pair of separate conductive strips along the inside surface of the bond shelf, the portion of the conductive material is removed by drilling into the edge of the bond shelf including the conductive material and the inside surface.

41. (Currently Amended) The method of claim ~~39~~40, wherein
the portion of the conductive material is removed by
etching away a portion of the conductive material from the inside surface of the bond shelf.
42. (Currently Amended) The method of claim ~~39~~40, wherein,
the plating of the conductive material onto the inside surface of the bond shelf includes
masking surfaces of the housing that are not to be plated and
leaving surfaces of the housing unmasked that are to be plated, including the inside surface of the bond shelf that is to be plated.
43. (Previously Presented) The method of claim 42, wherein
the plating of the conductive material further includes
plating copper onto the unmasked surfaces of the housing, and
plating gold onto the copper.

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44. (Previously Presented) The method of claim 43, wherein
the portion of the conductive material is removed by
drilling into the edge of the bond shelf including the conductive material and the
inside surface.
45. (Withdrawn) The method of claim ~~39~~40, wherein
the plating of the conductive material further includes
plating a portion of the conductive material from the inside surface around onto
the top surface of the bond shelf to couple to the bond pad on the top surface of the bond
shelf.
46. (Withdrawn) The method of claim 45, wherein
the portion of the conductive material plated around onto the inside surface of the
bond shelf to further anchor the conductive material to the housing.
47. (Withdrawn) The method of claim ~~39~~40, wherein
the plating of the conductive material further includes
plating a portion of the conductive material from the inside surface around onto
the top surface of the bond shelf to form another bond pad on the top surface of the bond
shelf.
48. (Withdrawn) The method of claim 47, wherein
the portion of the conductive material plated around onto the top surface of the

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bond shelf to further anchor the conductive material to the housing.

49. (Withdrawn) The method of claim ~~39~~40, further comprising:

mounting an integrated circuit to the housing and connecting the integrated circuit to the bond pad.

50. (Cancelled).

51. (Currently Amended) The method as recited in claim ~~50~~52, wherein

the conductive strip is formed by plating a conductive material onto the rectangular cavity wall of the bond shelf.

52. (Currently Amended) A The method as recited in claim 50, wherein for assembling an electronic package, comprising:

forming a housing which has a plurality of bond pads located on a top surface of a bond shelf, the bond shelf forming a rectangular cavity wall along an inner side of the bond shelf;

forming a conductive strip lengthwise along the rectangular cavity wall of the bond shelf;
and

removing portions of the conductive strip along the rectangular cavity wall of the bond shelf to form a plurality of separate conductive strips along the rectangular cavity wall of the bond shelf, portions of the conductive strip are removed by drilling a portion of the rectangular cavity wall of the bond shelf including the conductive strip.

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53. (Currently Amended) The method as recited in claim ~~50~~52, further comprising:
mounting an integrated circuit to the housing and connecting the integrated circuit to at
least one of the plurality of bond pads.

54. (Currently Amended) The method as recited in claim ~~50~~52, wherein
portions of the conductive strip are removed by
etching away portions of the conductive material on the rectangular cavity wall of
the bond shelf.

55. (Currently Amended) The method as recited in claim ~~50~~52, wherein
the conductive strip is formed along the rectangular cavity wall of the bond shelf by
masking surfaces of the bond shelf except for portions of the bond shelf to be
plated, the rectangular cavity wall of the bond shelf being unmasked, and
plating a conductive material onto the rectangular cavity wall of the bond shelf.